



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4206G			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000982390							
<b>Package</b>	PG-DSO-14-22			<b>Weight*</b>	142.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.173	2.22	2.22	22196	22196
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8442	
wire	non noble metal	copper	7440-50-8	49.007	34.28	35.17	342795	351765
	noble metal	gold	7440-57-5	0.237	0.17	0.17	1658	1658
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1206
plastics	plastics	epoxy resin	-	7.928	5.55		55454	
	inorganic material	silicondioxide	60676-86-0	78.072	54.60	60.27	546098	602758
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8577	8577
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7203	7203
glue	plastics	acrylic resin	-	0.184	0.13		1285	
	noble metal	silver	7440-22-4	0.652	0.46	0.59	4558	5843
*deviation	< 10%			Sum in total:		100,00		1000000

### Important Remarks:

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